Product Document

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AS5261

General Description

12-Bit Automotive Angle Position Sensor

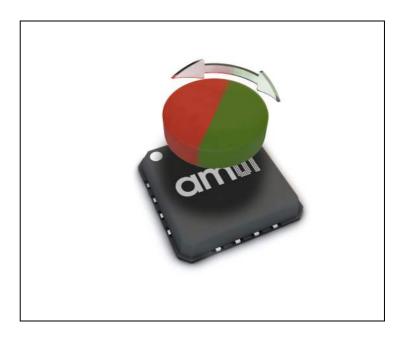
The AS5261 is a contactless magnetic angle position sensor for accurate angular measurement over a full turn of 360°. A sub range can be programmed to achieve the best resolution for the application. It is a system-on-chip, combining integrated Hall elements, analog front end, digital signal processing and best in class automotive protection features in a single device.

To measure the angle, only a simple two-pole magnet, rotating over the center of the chip, is required. The magnet may be placed above or below the IC.

The absolute angle measurement provides instant indication of the magnet's angular position with a resolution of $0.022^\circ = 16384$ positions per revolution. According to this resolution the adjustment of the application specific mechanical positions are possible. The angular output data is available over a 12 bit PWM output.

The AS5261 operates at a supply voltage of 5V and the supply and output pins are protected against overvoltage up to +20V. In addition the supply pins are protected against reverse polarity up to -20V.

Figure 1: Typical Arrangement of AS5261 and Magnet



Ordering Information and Content Guide appear at end of datasheet.



Key Benefits & Features

The benefits and features of AS5261, 12-Bit Automatic Angle Position Sensor are listed below:

Figure 2: Added Value of Using AS5261

Benefits	Features
Great flexibility on angular excursion	360° contactless high resolution angular position sensing
Simple programming	 User programmable start and end point of the application region Saw tooth mode 1-4 slopes per revolution Clamping levels Transition point
Failure diagnostics	Broken GND and VDD detection for all external load cases
High-Resolution output signal	12-Bit pulse width modulated (PWM) output
 Ideal for applications in harsh environments due to contactless position sensing 	• Wide temperature range: - 40°C to 150°C
Stacked die redundant approach	Small Pb-free package: MLF 16 6x6 (with dimple)

Applications

The AS5261 is ideal for automotive applications like:

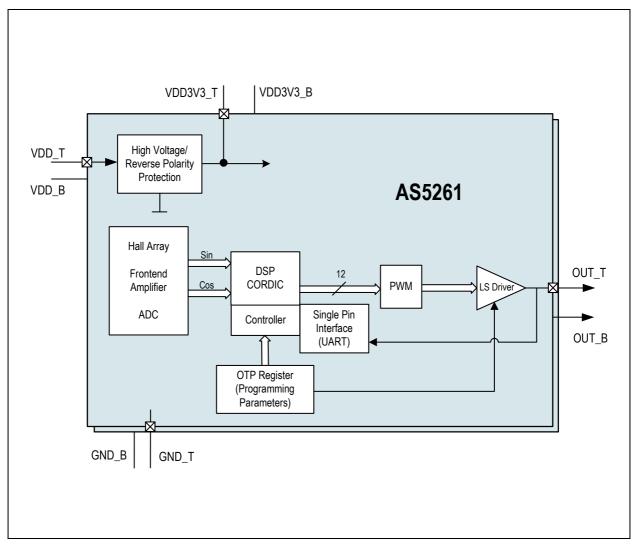
- Throttle and valve position sensing
- Gearbox position sensor
- Pedal position sensing
- Contactless potentiometers



Block Diagram

The functional blocks of this device are shown below:

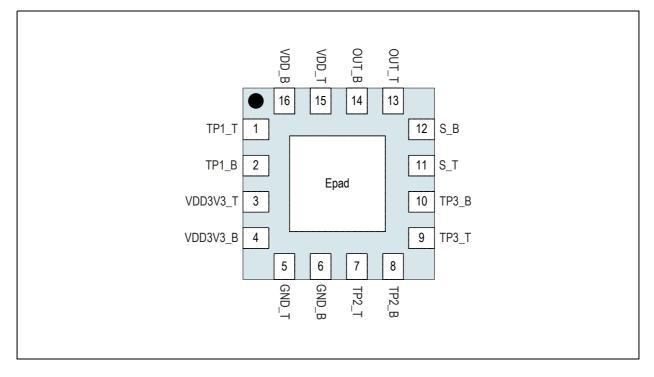






Pin Assignment

Figure 4: MLF-16 Pin Configuration (Top View)



Pin Description

Figure 5: MLF-16 Pin Description

Pin Number	Pin Name	Pin Type	Description
1	TP1_T	DIO/AIO application.	
2	TP1_B	Multi purpose pin	Test pin for fabrication. Connected to ground in the application.
3	VDD3V3_T	AIO	Output of the LDO. 1µF required.
4	VDD3V3_B	Alo	Output of the LDO. 1µF required.
5	GND_T	Supply pin	Ground pin. Connected to ground in the application.
6	GND_B	зарру ріп	Ground pin. Connected to ground in the application.

Pin Number	Pin Name	Pin Type	Description
7	TP2_T		Test pin for fabrication. Connected to ground in the application.
8	TP2_B	DIO/AIO Multi purpose pin	Test pin for fabrication. Connected to ground in the application.
9	TP3_T		Test pin for fabrication. Left open in the application.
10	TP3_B		Test pin for fabrication. Left open in the application.
11	S_T	AIO	Test pin for fabrication. Connected to OUT_T in the application. (special case for the connection possible \rightarrow 4-wire mode)
12	S_B	AIO	Test pin for fabrication. Connected to OUT_B in the application. (special case for the connection possible \rightarrow 4-wire mode)
13	OUT_T	Digital output/Digital	PWM output pin. Open drain configuration. Programming pin.
14	OUT_B	PWM output	PWM output pin. Open drain configuration. Programming pin.
15	VDD_T	Supply pin	Positive supply pin. This pin is over voltage protected.
16	VDD_B	σαρριγ ριπ	Positive supply pin. This pin is over voltage protected.

Absolute Maximum Ratings

Stresses beyond those listed in Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in Electrical Characteristics is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Figure 6: Absolute Maximum Ratings

Symbol	Parameter	Min	Мах	Units	Comments
	El	ectrical F	Paramete	rs	
V _{DD}	DC supply voltage at pin VDD Overvoltage	-20	20	V	No operation
V _{OUT}	Output voltage OUT	-0.3	20	V	Permanent
V _{DD3V3}	DC supply voltage at pin V _{DD3V3}	-0.3	5	V	
۱ _{scr}	Input current (latchup immunity)	-100	100	mA	Norm: AEC-Q100-004
	Ele	ectrostati	c Dischar	ge	
ESD	Electrostatic discharge	±	:2	kV	Norm: AEC-Q100-002
	Temperature	Ranges a	nd Stora	ge Conditio	ons
T _{Strg}	Storage temperature	-55	150	°C	Min -67°F; Max 257°F
T _{Body}	Body temperature		260	۰C	The reflow peak soldering temperature (body temperature) specified is in accordance with IPC/JEDEC J-STD-020 "Moisture/Reflow Sensitivity Classification for Non-Hermetic Solid State Surface Mount Devices". The lead finish for Pb-free leaded packages is matte tin (100% Sn).
RH _{NC}	Relative humidity non-condensing	5	85	%	
MSL	Moisture Sensitivity Level		3		Represents a maximum floor life time of 168h

Electrical Characteristics

Operating Conditions

In this specification, all the defined tolerances for external components need to be assured over the whole operation conditions range and also over lifetime.

Figure 7: Operating Conditions

Symbol	Parameter	Conditions	Min	Тур	Мах	Units
T _{AMB}	Ambient temperature	-40°F to 302°F	-40		150	°C
I _{supp}	Supply current	Only for one die. Must be multiplied by 2			10	mA
V _{DD}	Supply voltage at pin VDD		4.5	5.0	5.5	V

Magnetic Input Specification

 T_{AMB} = -40°C to 150°C, V_{DD} = 4.5V to 5.5V (5V operation), unless otherwise noted.

Two-Pole Cylindrical Diametrically Magnetized Source

Figure 8: Magnetic Input Specification

Symbol	Parameter	Conditions	Min	Тур	Мах	Units
B _{pk}	Magnetic input field amplitude	Required vertical component of the magnetic field strength on the die's surface, measured along a concentric circle with a radius of 1.25 mm	30		70	mT
B _{pkext}	Magnetic input field amplitude (extended) default setting	Required vertical component of the magnetic field strength on the die's surface, measured along a concentric circle with a radius of 1.25 mm. Increased sensor output noise.	10		90	mT
B _{off}	Magnetic offset	Constant magnetic stray field			± 5	mT
D _{isp}	Displacement radius	Offset between defined device center and magnet axis. Dependent on the selected magnet. Including Eccentricity		1		mm



Electrical System Specifications

T_{AMB} = -40°C to 150°C, V_{DD} = 4.5V - 5.5V (5V operation), Magnetic Input Specification, unless otherwise noted.

Figure 9: Electrical System Specifications

Symbol	Parameter	Conditions	Min	Тур	Max	Units
RES	Resolution PWM Output	Range > 90°			12	bit
INL _{opt}	Integral non-linearity (optimum)	Best aligned reference magnet at 25°C over full turn 360°.			0.5	deg
INL _{temp}	Integral non-linearity (optimum)	Best aligned reference magnet over temperature -40 -150° over full turn 360°.			0.9	deg
INL	Integral non-linearity	Best aligned reference magnet over temperature -40 -150° over full turn 360° and displacement			1.4	deg
ON _{F0}		At 14 bit angular information, 360º mode. Internal Filter disabled.			±5	LSB
ON _{F1}	Output Noise	At 14 bit angular information, 360º mode. Filter setting 1.			±3	LSB
ON _{F2}	output Noise	At 14 bit angular information, 360º mode. Filter setting 2.			±2	LSB
ON _{F3}		At 14 bit angular information, 360º mode. Filter setting 3. Jitter free.			±0.5	LSB
t _{PwrUp}	Power-up time 0-5V	Power up time 5V operation. Default Power up.			10	ms
t _{delay}	System propagation delay absolute output: delay of ADC, DSP and absolute interface				300	μs

Timing Characteristics

Figure 10: Timing Conditions

Symbol	Parameter	Conditions	Min	Тур	Max	Units
T _{DETWD}	WachDog error detection time				12	ms

Detailed Description

The AS5261 is manufactured in a CMOS process and uses a spinning current Hall technology for sensing the magnetic field distribution across the surface of the chip. This IC consists of two galvanic isolated dies. All following in and register names refers to one die.

The integrated Hall elements are placed around the center of the device and deliver a voltage representation of the magnetic field at the surface of the IC.

Through Sigma-Delta Analog / Digital Conversion and Digital Signal-Processing (DSP) algorithms, the AS5261 provides accurate high-resolution absolute angular position information. For this purpose a Coordinate Rotation Digital Computer (CORDIC) calculates the angle and the magnitude of the Hall array signals.

The DSP is also used to provide digital information at the outputs that indicate movements of the used magnet towards or away from the device's surface.

A small low cost diametrically magnetized (two-pole) standard magnet provides the angular position information.

The AS5261 senses the orientation of the magnetic field and calculates a 14-bit binary code. This code is mapped to a programmable output characteristic in a PWM duty cycle format. This signal is available at the pin (**OUT**).

The application angular region can be programmed in a user friendly way. The start angle position **T1** and the end point **T2** can be set and programmed according the mechanical range of the application with a resolution of 14 bits. In addition the **T1Y** and **T2Y** parameter can be set and programmed according the application. The transition point 0 to 360 degree can be shifted using the break point parameter **BP**. The voltage for clamping level low **CLL** and clamping level high **CLH** can be programmed with a resolution of 9 bits. Both levels are individually adjustable.

The output parameters can be programmed in an OTP register. No additional voltage is required to program the AS5261. The setting may be overwritten at any time and will be reset to default when power is cycled. To make the setting permanent, the OTP register must be programmed by using a lock bit the content could be frozen for ever.

The AS5261 is tolerant to magnet misalignment and unwanted external magnetic fields due to differential measurement technique and Hall sensor conditioning circuitry.

Operation

VDD Voltage Monitor

VDD Over Voltage Management. If the voltage applied to the **VDD** pin exceeds the over-voltage upper threshold for longer than the detection time the output is turned off. When the over voltage event has passed and the voltage applied to the **VDD** pin falls below the over-voltage lower threshold for longer than the recovery time the device enters the normal mode and the output is enabled.

VDD Under Voltage Management. When the voltage applied to the **VDD** pin falls below the under-voltage lower threshold for longer than the detection time the output is turned off. When the voltage applied to the **VDD** pin exceeds the under-voltage upper threshold for longer than the detection time the device enters the normal mode and the output is enabled.

PWM Output

By default (after programmed **CUST_LOCK** OTP bit) the PWM output mode is selected. The pin **OUT** provides a modulated signal that is proportional to the angle of the rotating magnet. Due to an intelligent approach a permanent short circuit will not damage the device. This is also feasible in a high voltage condition up to 20V and at the highest specified ambient temperature.

After the digital signal processing (DSP) a PWM engine provides the output signal.

The DSP maps the application range to the output characteristic. An inversion of the slope is also programmable to allow inversion of the rotation direction.

An on-chip diagnostic feature handles the error state at the output. Depending on the failure the output is in HiZ condition or indicates a PWM signal within the failure bands of 4 – 96% duty cycle (see Figure 18).



Programming Parameters

The PWM output characteristic is programmable by OTP. Depending on the application, the output can be adjusted. The user can program the following application specific parameters.

Figure 11: Programming Parameters

T1	Mechanical angle start point
T2	Mechanical angle end point
T1Y	% duty cycle level at the T1 position
T2Y	% duty cycle level at the T2 position
CLL	Clamping Level Low
CLH	Clamping Level High
BP	Break point (transition point 0 to 360°)

These parameters are input parameters. Using the available programming software and programmer these parameters are converted and finally written into the AS5261 128 bit OTP memory.

Application Specific Angular Range Programming

The application range can be selected by programming **T1** with a related **T1Y** and **T2** with a related **T2Y** into the AS5261. The clamping levels **CLL** and **CLH** can be programmed independent from the **T1** and **T2** position and both levels can be separately adjusted.

Figure 12: Programming of an Individual Application Range

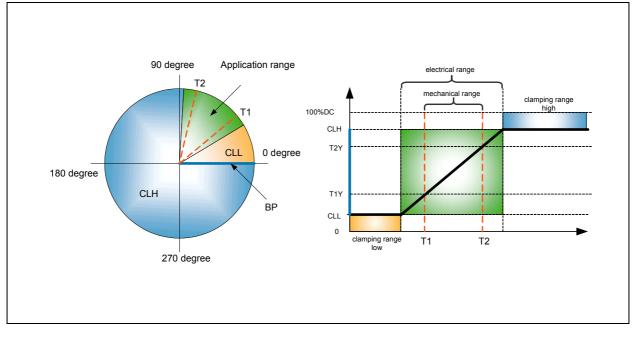


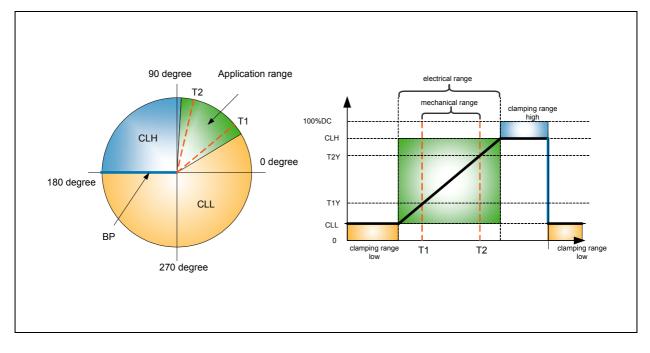
Figure 12 shows a simple example of the selection of the range. The mechanical starting point **T1** and the mechanical end point **T2** are defining the mechanical range. A sub range of the internal CORDIC output range is used and mapped to the needed output characteristic. The PWM output signal has 12 bit, hence the level **T1Y** and **T2Y** can be adjusted with this resolution. As a result of this level and the calculated slope the clamping region low is defined. The break point **BP** defines the transition between **CLL** and **CLH**. In this example the **BP** is set to 0°. The **BP** is also the end point of the clamping level high **CLH**. This range is defined by the level CLH and the calculated slope. Both clamping levels can be set independently form each other. The minimum application range is 9.8°.



Application Specific Programming of the Break Point

The break point **BP** can be programmed as well with 14 bits. This is important when the default transition point is inside the application range. In such a case the default transition point must be shifted out of the application range. The parameter **BP** defines the new position.

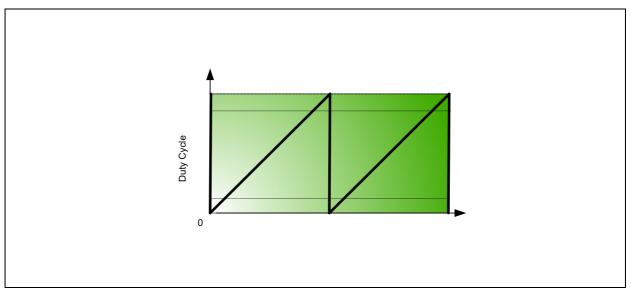
Figure 13: Individual Programming of the Break Point BP



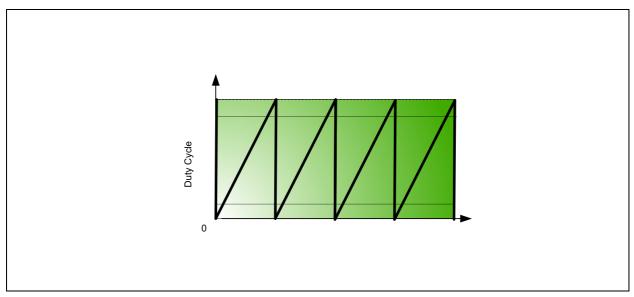
Multiple Slope Output

The AS5261 can be programmed to multiple slopes. Where one programmed reference slope characteristic is copied to multiple slopes. Two, three and four slopes are selectable by the user OTP bits **QUADEN (1:0)**. In addition to the steepness of the slope the clamping levels can be programmed as well.











Resolution of Parameters

The programming parameters have a wide resolution of up to 14 bits.

Figure 16: Resolution of the Programming Parameters

Symbol	Parameter	Resolution	Note
T1	Mechanical angle start point	14 bits	
T2	Mechanical angle stop point	14 bits	
T1Y	Mechanical start voltage level	12 bits	
T2Y	Mechanical stop voltage level	12 bits	
CLL	Clamping level low	9 bits	
CLH	Clamping level high	9 bits	
BP	Break point	14 bits	

Figure 17: Overview of the Output Range

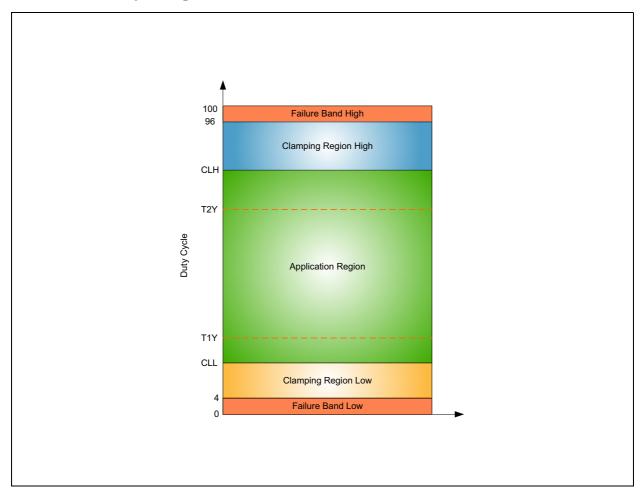


Figure 17 gives an overview about the different ranges. The failure bands are used to indicate a wrong operation of the AS5261. This can be caused due to a broken supply line. By using the specified load resistors the output level will remain in these bands during a fail. It is recommended to set the clamping level **CLL** above the lower failure band and the clamping level **CLH** below the higher failure band.

 $C_{LOAD} \le 33 nF$, $R_{PU} = 1 k\Omega$ to $10 k\Omega$

Figure 18: Different Failure Cases of AS5261

Туре	Failure Mode	Symbol	Failure Band	Note
	Out of magnetic range (too less or too high magnetic input)	MAGRng	High/Low	Programmable by OTP bit DIAG_HIGH
	CORDIC overflow	COF	High/Low	Programmable by OTP bit DIAG_HIGH
Internal alarms (failures)	Offset compensation finished	OCF	High/Low	Programmable by OTP bit DIAG_HIGH
	Watchdog fail	WDF	High/Low	Programmable by OTP bit DIAG_HIGH
	Oscillator fail	OF	High/Low	Programmable by OTP bit DIAG_HIGH
	Overvoltage condition	OV		Dependant on the load
Application	Broken VDD	BVDD	High	resistor
Application related failures	Broken VSS	BVSS		Pull up $ ightarrow$ failure band high
	Short circuit output	SCO	High	Switch off \rightarrow short circuit dependent

For efficient use of diagnostics, it is recommended to program to clamping levels **CLL** and **CLH**.

Hysteresis Function

AS5261 device includes a hysteresis function to avoid sudden jumps from CLH to CLL and vice versa caused by noise in the full turn configuration.

The hysteresis amplitude can be selected via the OTP bits **HYSTSEL<1:0>**.



PWM Output Driver Parameters

The output stage is configured in a open drain output.

The PWM duty cycle represents the angular output data. All programming features are available for the PWM mode as well. The PWM period is programmable in four steps and can be programmed by **PWMF<2:0**>.

 $C_{LOAD} \le 33 nF$, $R_{PU} = 1 k\Omega$ to $10 k\Omega$

Figure 19: PWM Parameters Output Driver

Symbol	Parameter	Conditions	Min	Тур	Max	Units
PWMF1	PWM frequency 7	PWMF<2:0>=111	109.86	122	134.28	Hz
PWMF2	PWM frequency 6	PWMF<2:0>=110	179.78	200	219.73	Hz
PWMF3	PWM frequency 5	PWMF<2:0>=101	219.73	244	268.55	Hz
PWMF4	PWM frequency 4	PWMF<2:0>=100	329.59	366	402.83	Hz
PWMF5	PWM frequency 3	PWMF<2:0>=011	494.38	549	604.25	Hz
PWMF6	PWM frequency 2	PWMF<2:0>=010	659.18	732	805.66	Hz
PWMF7	PWM frequency 1	PWMF<2:0>=001	988.77	1100	1208.50	Hz
PWMF8	PWM frequency 0	PWMF<2:0>=000	1977.54	2197	2416.2	Hz
PWMDC	PWM duty cycle range	info parameter	4		96	%
PWMVOL	Output voltage low	IOUT=5mA	0		0.4	V
PWMSRF	PWM slew rate (falling edge)	Between 75% and 25% RPUOUT=4KΩ; CLOUT=1nF VDD=5V	1	2	4	V / μs



Application Information

Recommended Application Schematic

Figure 20 shows the recommended schematic in the application. All components marked with (*) are optional and can be used to further increase the EMC.

Figure 20: Recommended Schematic of Pull-Up Configuration

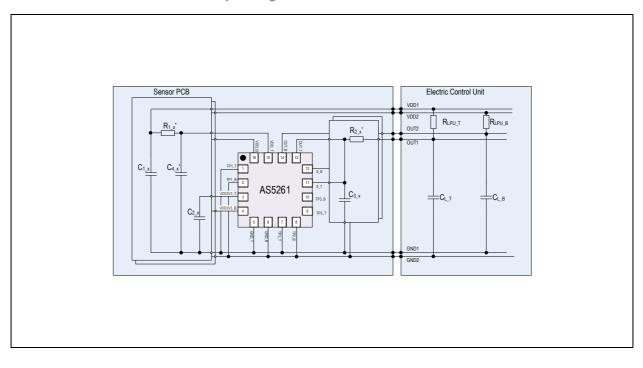


Figure 21: External Components

Symbol	Parameter	Min	Тур	Мах	Units	Note
C ₁	VDD buffer capacitor	0.8	1	1.2	μF	Low ESR 0.3 Ω
C ₂	VDD3V3 regulator capacitor	0.8	1	1.2	μF	Low ESR 0.3 Ω
C ₃	OUT load capacitor (sensor PCB)	0		4.7	nF	
C ₄ *	VDD capacitor (optional)		4.7		nF	Do not increase due to programming over output.
R_1^*	VDD serial resistor (optional)		10		Ω	
CL	OUT load capacitor (ECU)	0		33	nF	
R ₂ *	OUT serial resistor (optional)		50		Ω	
R _{LPU}	OUT pull-up resistance	4		10	kΩ	

Programming the AS5261

The AS5261 programming is a one-time-programming (OTP) method, based on polysilicon fuses. The advantage of this method is that no additional programming voltage is needed. The internal LDO provides the current for programming.

The OTP consists of 128 bits; several bits are available for user programming. In addition factory settings are stored in the OTP memory. Both regions are independently lockable by build in lock bits.

A single OTP cell can be programmed only once. Per default, the cell is "0"; a programmed cell will contain a "1". While it is not possible to reset a programmed bit from "1" to "0", multiple OTP writes are possible, as long as only unprogrammed "0"-bits are programmed to "1".

Independent of the OTP programming, it is possible to overwrite the OTP register temporarily with an OTP write command. This is possible only if the user lock bit is not programmed.

Due to the programming over the output pin the device will initially start in the communication mode. In this mode the digital angle value can be read with a specific protocol format. It is a bidirectional communication possible. Parameters can be written into the device. A programming of the device is triggered by a specific command. With another command (pass2func) the device can be switched into operation mode. In case of a programmed user lock bit the AS5261 automatically starts up in the functional operation mode. No communication of the specific protocol is possible after this.

A standard half duplex UART protocol is used to exchange data with the device in the communication mode.

UART Interface for Programming

The AS5261 uses a standard UART interface with a byte for address and two bytes for the data content. The read or write mode is selected in the first byte. An even parity for every byte. The timing (baudrate) is selected by the AS5261 over an initial command from the master. The baud rate register can be read and overwritten. The keep synchronization it AS5261 synchronizes art every Start bit. This happens during a standard write access 3 times.

A time out function detects not complete commands and resets the AS5261 UART after the timeout period.



Frame Organization

Each frame is composed by 24 bits. The first byte (Address or Command) of the frame specifies the read/write operation with the register address or is used for a command. 16 data bits contains the communication data. There will be no operation in case of the usage of a not specified CMD. The UART programming interface block of the AS5261 can operate in slave communication or master communication mode. In the slave communication mode the AS5261 receives the data. The programming tool is the driver of the single communication line. In case of the master comunication mode the AS5261 transmits data in the frame format. The single communication line can be pulled down by the AS5261.

Figure 22: OTP Commands and Communication

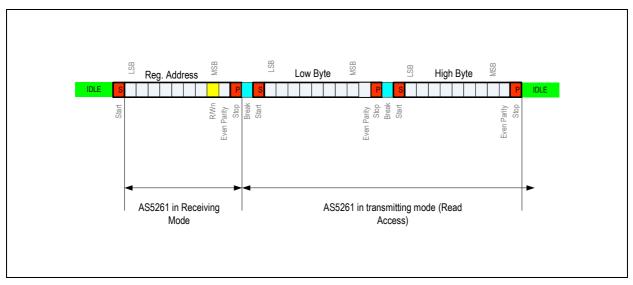
Possible Interface Commands	Address / Command	AS5X63 Communication Mode	Description
WRITE	0x00-0x0F (OTP) 0x10-0x1F (SFR) 0x20-0xFF (Special Mode)	SLAVE	Write related to the address the user data
READ	0x00-0x0F (OTP) 0x10-0x1F (SFR) 0x20-0xFF (Special Mode)	SLAVE and MASTER	Read related to the address the user data
FUSE	0x22+ key	SLAVE	Command for permanent programming
PASS2FUNC	0x23+ key	SLAVE	Change operation mode from communication to operation



READ

Figure 23 shows the format of the frame.





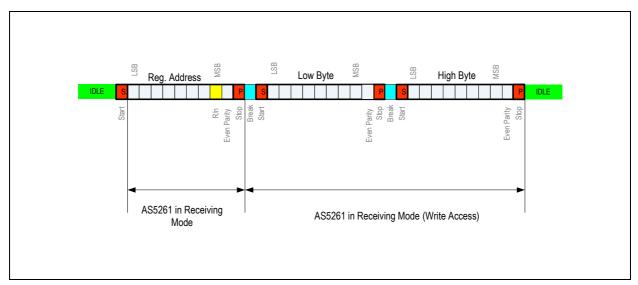
The R/Wn bit in the first byte selects the mode. Between the data packets is always a break state. The break state has the same length as the other data bits.

An even parity bit is used to guarantee a correct data transmission. The parity bit is generated by the 8 bits.

WRITE

Figure 24 shows the format of the frame.

Figure 24: Organization of the WRITE Command



Baud Rate Setup

Due to the internal RC oscillator the AS5261 needs to synchronize to the master. This happens after startup with the first baud rate command. This register address is reserved after the first successful setup for a possible manual setting of the baud rate.

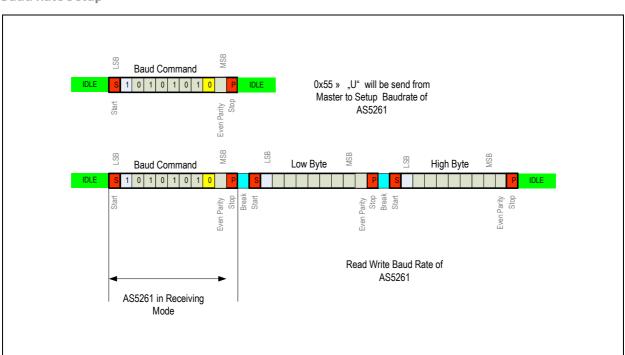


Figure 25: Baud Rate Setup



OTP Programming Data

Figure 26: OTP Memory Map

Data Byte	Bit Number	Symbol	Default	Description	
	0		0		
	1		0		
	2		0		
DATA15 (0x0F)	3		0		
	4		0		
	5		0		
	6		0		
	7		0		Fac
	0	Factory	0	ams (reserved)	Factory Settings
	1	Settings	0		Settii
	2		0		ngs
DATA14 (0x0E)	3		0		
	4		0		
	5		0		
	6		0		
	7		0		
	0		0		
	1		0		
	2	CUSTID<0>	0		
DATA13 (0x0D)	3	CUSTID<1>	0		ç
	4	CUSTID<2>	0		uston
	5	CUSTID<3>	0	Customer Identifier	ner Su
	6	CUSTID<4>	0		Customer Settings
	7	CUSTID<5>	0		sť
DATA12 (0x0C)	0	CUSTID<6>	0		

Data Byte	Bit Number	Symbol	Default	Description	
DATA11 (0x0B)	7	CLH<0>	0		
	0	CLH<1>	0		
	1	CLH<2>	0		0
	2	CLH<3>	0		uston
DATA10 (0x0A)	3	CLH<4>	0	Clamping Level High	ner S
	4	CLH<5>	0		Customer Settings
	5	CLH<6>	0		gs
	6	CLH<7>	0		
	7	CLH<8>	0		



Data Byte	Bit Number	Symbol	Default	Description	
	0	CLL<0>	0		
	1	CLL<1>	0		
	2	CLL<2>	0		
DATA9 (0x09)	3	CLL<3>	0		
	4	CLL<4>	0	Clamping Level Low	
	5	CLL<5>	0		
	6	CLL<6>	0		
	7	CLL<7>	0		
	0	CLL<8>	0		
	1	OFFSET<0>	0		
	2	OFFSET<1>	0		Cust
DATA8 (0x08)	3	OFFSET<2>	0		Customer Settings
	4	OFFSET<3>	0		r Sett
	5	OFFSET<4>	0		ings
	6	OFFSET<5>	0		
	7	OFFSET<6>	0		
	0	OFFSET<7>	0	Offset	
	1	OFFSET<8>	0		
	2	OFFSET<9>	0		
DATA7 (0x07)	3	OFFSET<10>	0		
	4	OFFSET<11>	0		
	5	OFFSET<12>	0		
	6	OFFSET<13>	0		
	7	OFFSET<14>	0		

Data Byte	Bit Number	Symbol	Default	Description	
	0	OFFSET<15>	0		
	1	OFFSET<16>	0		
	2	OFFSET<17>	0	Offset	
	3	OFFSET<18>	0		
DATA6 (0x06)	4	OFFSET<19>	0		
	5	GAIN<0>	0		
	6	GAIN<1>	0		
	7	GAIN<2>	0		
	0	GAIN<3>	0		
	1	GAIN<4>	0		
	2	GAIN<5>	0		
DATA5 (0x05)	3	GAIN<6>	0		
	4	GAIN<7>	0		
	5	GAIN<8>	0	Scale Factor	Cust
	6	GAIN<9>	0		Customer Settings
	7	GAIN<10>	0		r Seti
	0	GAIN<11>	0		tings
	1	GAIN<12>	0		
	2	GAIN<13>	0		
DATA4 (0x04)	3	GAIN<14>	0		
	4	GAIN<15>	0		
	5	GAIN<16>	0		
	6	BP<0>	0		
	7	BP<1>	0		
	0	BP<2>	0]	
	1	BP<3>	0	Break Point	
DATA3 (0x003)	2	BP<4>	0		
	3	BP<5>	0]	
	4	BP<6>	0		
	5	BP<7>	0		



Data Byte	Bit Number	Symbol	Default	Description		
	6	BP<8>	0			
	7	BP<9>	0			
	0	BP<10>	0	Break Point		
	1	BP<11>	0	DieakToint		
	2	BP<12>	0			
	3	BP<13>	0			
DATA2 (0x02)	4	ANGLERNG	0	Sector selection 0=Angular Sector≥22.5 degrees; 1=Angular Sector<22.5 degrees	Ť	
	5	DIAG_HIGH	0	Failure Band Selection 0=Failure Band Low 1=Failure Band High	6	
	6	QUADEN<0>	0	Quadrant Mode Enable	istom	
	7	QUADEN<1>	0	00=1quadrant; 01=2quadrants; 10=3 quadrants; 11=4 quadrants	Customer Settings	
	0	AIRGAPSEL	0	Magnetic input range extension 0:extended range; 1=normal range	. •	
	1	HYSTSEL<0>	0	Hysteresis selection		
DATA1 (0x01)	2	HYSTSEL<1>	0	00=no hysteresis; 01: 56LSB; 10=91LSB; 11=137LSB		
	3	Not used	0			
	4	Not used	0			
	5	Not used	0			
	6	Not used	0			
	7	Not used	0			

Data Byte	Bit Number	Symbol	Default	Description	
	0	RED_ADD<0>	0		
	1	RED_ADD<1>	0	Redundancy Address Identify the address of the	
	2	RED_ADD<2>	0	byte containing the bit to be changed	Cus
	3	RED_ADD<3>	0		tome
DATA0 (0x00)	4	RED_BIT<0>	0	Redundancy Bit	r Set
	5	RED_BIT<1>	0	 Identify the position of the bit to be changed in the byte at the address RED_ADD<3:0> 	Customer Settings
	6	RED_BIT<2>	0		
	7	CUST_LOCK	0	Lock bit for Customer Area	

READ / WRITE Register Map

Figure 27: Read/Write Registers

Data Byte	Bit Number	Symbol	Default	Description		
	0	BAUDREG<0>	0			
	1	BAUDREG<1>	0			
	2	BAUDREG<2>	0			
	3	BAUDREG<3>	0			
DATA0 (0x20)	4	BAUDREG<4>	0	UART Baud Rate Register		
	5	BAUDREG<5>	0			
	6	BAUDREG<6>	0			
	7	BAUDREG<7>	0			
	0	BAUDREG<8>	0			
	1	Not used	0			
	2	Not used	0	A read command returns all data bits at 0	Я	
DATA1 (0x21)	3	Not used	0		Read/Write Area	
	4	Not used	0		Nrite	
	5	Not used	0		Area	
	6	Not used	0			
	7	Not used	0			
	0	Not used	0			
	1	Not used	0			
	2	Not used	0			
	3	Not used	0			
DATA2 (0x22)	4	Not used	0			
	5	R1K10K<0>	0	Selection of the reference resistance used for OTP		
	6	R1K10K<1>	0	download		
	7	DSPRN	0	Resetn of the Digital Signal Processing circuit		



READ Only Register Map

Figure 28: Read Only Registers

Data Byte	Bit Number	Symbol	Default	Description	
	0	Not used	0	A read command returns 0	
	1	OFFSETFINISHED	0	Offset compensation finished	
	2	AGCFINISHED	0	AGC loop compensation finished	
	3	CORDICOVF	0	Overflow of the CORDIC	
DATA0 (0x28)	4	AGCALARML	0	AGC loop saturation because of B field too strong	
	5	AGCALARMH	0	AGC loop saturation because of B field too weak	
	6	OTP_RES	0	0=1K resistance selected for OTP download; 1=10K resistance selected for OTP download	Read Area
	7	PARITY_ERR	0	UART parity error flag	עפ
	0	CORDICOUT<0>	0		
	1	CORDICOUT<1>	0		
	2	CORDICOUT<2>	0		
DATA1 (0x29)	3	CORDICOUT<3>	0		
DAIAT (0829)	4	CORDICOUT<4>	0	- CORDIC Output	
	5	CORDICOUT<5>	0		
	6	CORDICOUT<6>	0		
	7	CORDICOUT<7>	0]	



Data Byte	Bit Number	Symbol	Default	Description	
	0	CORDICOUT<8>	0		
	1	CORDICOUT<9>	0		
	2	CORDICOUT<10>	0	CORDIC Output	
DATA2 (0x2A)	3	CORDICOUT<11>	0	condic output	
DAIAZ (0XZA)	4	CORDICOUT<12>	0		
	5	CORDICOUT<13>	0		
	6	Not used	0	A read command returns all	
	7	Not used	0	data bits at 0	
	0	DSPOUT<0>	0		
	1	DSPOUT<1>	0		
	2	DSPOUT<2>	0		
DATA3 (0x2B)	3	DSPOUT<3>	0		Read
	4	DSPOUT<4>	0		Read Area
	5	DSPOUT<5>	0	DSP Output	_
	6	DSPOUT<6>	0		
	7	DSPOUT<7>	0		
	0	DSPOUT<8>	0		
	1	DSPOUT<9>	0		
	2	DSPOUT<10>	0		
DATA4 (0x2C)	3	DSPOUT<11>	0		
	4	Not used	0		
	5	Not used	0	A read command returns all	
	6	Not used	0	data bits at 0	
	7	Not used	0		

Data Byte	Bit Number	Symbol	Default	Description		
	0	AGCVALUE<0>	0			
	1	AGCVALUE<1>	0			
	2	AGCVALUE<2>	0			
DATA5 (0x2D)	3	AGCVALUE<3>	0	AGC Value		
	4	AGCVALUE<4>	0			
	5	AGCVALUE<5>	0			
	6	AGCVALUE<6>	0			
	7	AGCVALUE<7>	0			
	0	MAG<0>	0			
	1	MAG<1>	0			
	2	MAG<2>	0			
DATA6 (0x2E)	3	MAG<3>	0	Magnitude of magnetic field	Read	
DAIAO (0X2E)	4	MAG<4>	0	- Magnitude of magnetic field	Read Area	
	5	MAG<5>	0		2	
	6	MAG<6>	0			
	7	MAG<7>	0			
	0	Not used	0			
	1	Not used	0			
	2	Not used	0			
DATA7 (0x2F)	3	Not used	0	A read command returns all		
	4	Not used	0	data bits at 0		
	5	Not used	0			
	6	Not used	0			
	7	Not used	0			

Special Registers

Figure 29: Special Registers

Data Byte	Bit Number	Symbol	Default	Description	
	0	AS5261KEY<0>	0		
	1	AS5261KEY<1>	0		
	2	AS5261KEY<2>	0	AS5261 KEY<15:0>=0101 0001 0110 0010 A write command with data different from AS5261 KEY is not executed	
DATA0 (0x41)	3	AS5261KEY<3>	0		
	4	AS5261KEY<4>	0		
	5	AS5261KEY<5>	0	-	Fuse Register
	6	AS5261KEY<6>	0		
	7	AS5261KEY<7>	0	A write command with data	
	0	AS5261KEY<8>	0	not executed	
	1	AS5261KEY<9>	0	A read command returns all data bits at 0	
	2	AS5261KEY<10>	0		
DATA1 (0x42)	3	AS5261KEY<11>	0		
	4	AS5261KEY<12>	0		
	5	AS5261KEY<13>	0		
	6	AS5261KEY<14>	0		
	7	AS5261KEY<15>	0		

Data Byte	Bit Number	Symbol	Default	Description	
	0	AS5261KEY<0>	0		
	1	AS5261KEY<1>	0		
	2	AS5261KEY<2>	0		
DATA0 (0x60)	3	AS5261KEY<3>	0		
	4	AS5261KEY<4>	0		
	5	AS5261KEY<5>	0		
	6	AS5261KEY<6>	0	AS5261 KEY<15:0>=0101 0001 0110 0010	Pass
	7	AS5261KEY<7>	0	A write command with data different from AS5261 KEY is	Pass2Func Register
	0	AS5261KEY<8>	0	not executed	c Reg
	1	AS5261KEY<9>	0	A read command returns all data bits at 0	jister
	2	AS5261KEY<10>	0		
DATA1 (0x61)	3	AS5261KEY<11>	0		
	4	AS5261KEY<12>	0		
	5	AS5261KEY<13>	0		
	6	AS5261KEY<14>	0		
	7	AS5261KEY<15>	0		



Programming Procedure

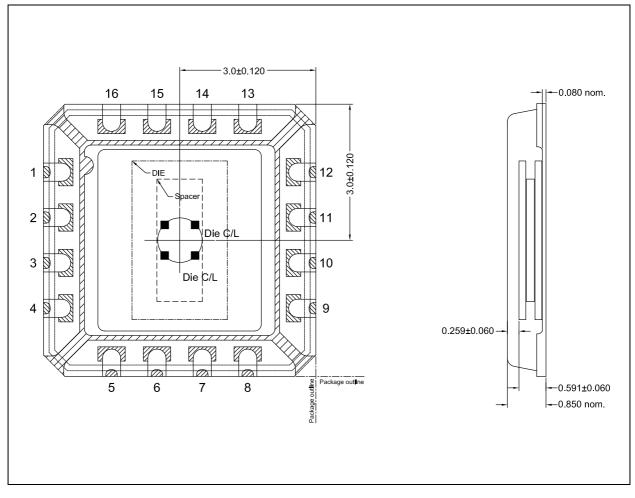
- Pull-Up on out pin
- VDD=5V
- Wait 10ms (after the startup time device enters communication mode)
- Write command: Trimming bits are written in the OTP RAM
- Read command: All the trimming bits are read back to check the correctness of the writing procedure.
- Write AS5261KEY in the Fuse register: The OTP RAM content is permanently transferred into the Poly Fuse cells.
- Wait 10 ms (fuse time)
- Write command, R1K_10K<1:0>=(11)b: Poly Fuse cells are downloaded into the RAM memory using a 10K resistance as reference.
- Wait 5 ms (download time)
- Read R1K_10K register, the expected value is 00b
- Write command, R1K_10K<1:0>=(11)b
- Read R1K_10K register, the expected value is (11)b. NB: Step11 and Step12 have to be consecutive.
- Read command: all the fused bits downloaded with 10K resistance are read back.
- Write command, R1K_10K=<1:0>=(10)b: Poly Fuse cells are downloaded into the RAM memory using a 1K resistance as reference.
- Wait 5 ms (download time)
- Read R1K_10K register, the expected value is (00)b
- Write command register, R1K_10K<1:0>=(10)b
- Read R1K_10K register, the expected value is (10)b NB: Step18 and Step19 have to be consecutive.
- Read command: All the fused bits downloaded with 1K resistance are read back.
- Check that read commands at Steps 5, 13 and 19 are matching
- Write AS5261 KEY in the Pass2Func register: Device enters normal mode.



Mechanical Data

The internal Hall elements are placed in the center of the package on a circle with a radius of 1.25mm.





Note(s) and/or Footnote(s):

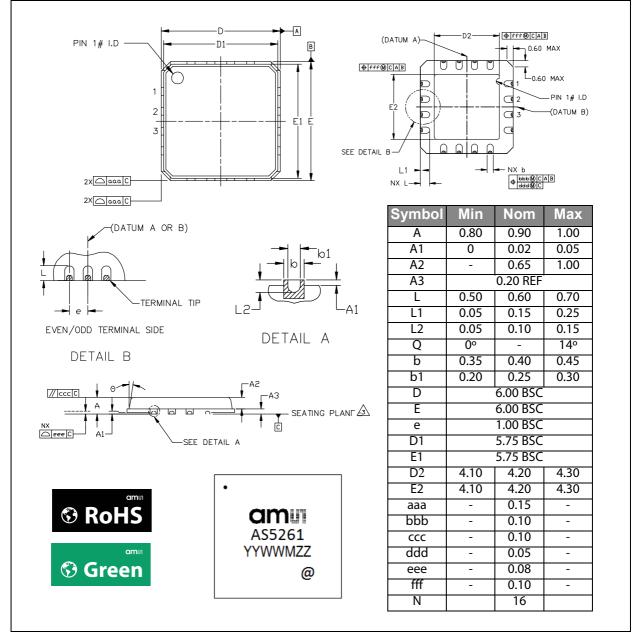
- 1. All dimensions in mm.
- 2. Die thickness 0.150mm nom.
- 3. Adhesive thickness 0.011mm nom.
- 4. Spacer thickness 0.178mm typ.



Package Drawings & Markings The d

The device is available in a MLF-16 package.

Figure 31: Package Drawings and Dimensions



Note(s) and/or Footnote(s):

1. Dimensions and tolerancing confirm to ASME Y14.5M-1994.

- 2. All dimensions are in millimeters. Angles are in degrees.
- 3. Bilaretal coplanarity zone applies to the exposed pad as well as the terminal.
- 4. Radius on the terminal is optional.
- 5. N is the total number of terminals.

Figure 32:

Package Marking: YYWWMZZ@

YY	ww	Μ	ZZ	@
Year	Week	Assembly plant identifier	Assembly traceability code	Sublot identifier



Ordering & Contact Information The devices are available Figure 33.

The devices are available as the standard products shown in Figure 33.

Figure 33: Ordering Information

Ordering Code	Description	Package	Delivery Form	Delivery Quantity
AS5261-HMFP	12-bit programmable redundant angle position	MLF 16 6x6	Tape & Reel	4000 pcs/reel
AS5261-HMFM	sensor with PWM outputs	MEI TO 0X0	Tape & Reel	500 pcs/reel

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Product Preview	Pre-Development	Information in this datasheet is based on product ideas in the planning phase of development. All specifications are design goals without any warranty and are subject to change without notice
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Revision Information

Changes from 1.1 (2012-Oct-31) to current revision 1-04 (2015-Dec-07)	Page			
1.1 (2012-Oct-31) to 1-02 (2015-Aug-07)				
Content was updated to the latest ams design				
Noise Suppressor section was removed				
Updated Key Benefits & Features	2			
Updated Figure 27	24			
Added Mechanical Data section	37			
Updated Package Drawings & Markings section	38			
Updated Figure 35	39			
1-02 (2015-Aug-07) to 1-03 (2015-Dec-03)				
Updated Detailed Description	9			
Updated Figure 11	11			
Updated Figure 16	15			
Updated Figure 30	36			
1-03 (2015-Dec-03) to 1-04 (2015-Dec-07)				
Updated Figure 2	2			
Updated Figure 26 [DATA11 (0x0B), DATA12 (0x0C)]	23			
Updated Mechanical Data section	36			

Note(s) and/or Footnote(s):

1. Page and figure numbers for the previous version may differ from page and figure numbers in the current revision.

2. Correction of typographical errors is not explicitly mentioned.

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amu

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